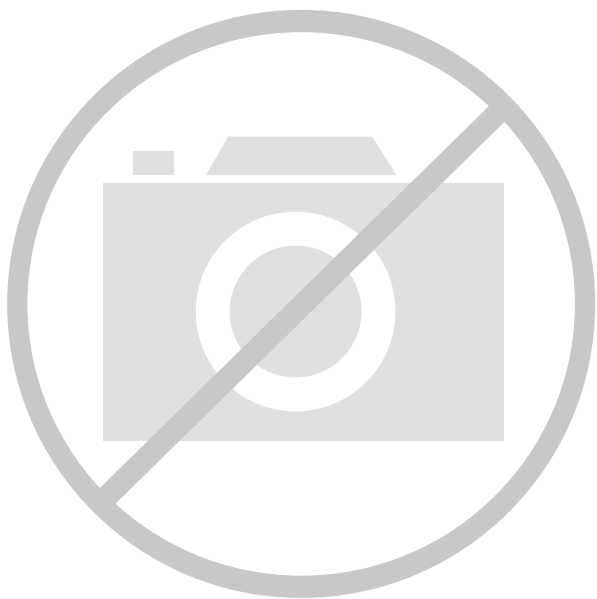




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	7776
Number of Logic Elements/Cells	34992
Total RAM Bits	589824
Number of I/O	724
Number of Gates	2188742
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1156-BBGA
Supplier Device Package	1156-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1600e-8fg1156c

Table 1: Virtex-E Field-Programmable Gate Array Family Members

Device	System Gates	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	BlockRAM Bits	Distributed RAM Bits
XCV50E	71,693	20,736	16 x 24	1,728	83	176	65,536	24,576
XCV100E	128,236	32,400	20 x 30	2,700	83	196	81,920	38,400
XCV200E	306,393	63,504	28 x 42	5,292	119	284	114,688	75,264
XCV300E	411,955	82,944	32 x 48	6,912	137	316	131,072	98,304
XCV400E	569,952	129,600	40 x 60	10,800	183	404	163,840	153,600
XCV600E	985,882	186,624	48 x 72	15,552	247	512	294,912	221,184
XCV1000E	1,569,178	331,776	64 x 96	27,648	281	660	393,216	393,216
XCV1600E	2,188,742	419,904	72 x 108	34,992	344	724	589,824	497,664
XCV2000E	2,541,952	518,400	80 x 120	43,200	344	804	655,360	614,400
XCV2600E	3,263,755	685,584	92 x 138	57,132	344	804	753,664	812,544
XCV3200E	4,074,387	876,096	104 x 156	73,008	344	804	851,968	1,038,336

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectI/O technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250 MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT} , the supply voltage for the internal logic and memory, is 1.8 V, instead of 2.5 V for Virtex devices. Advanced processing and 0.18 μ m design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3 V tolerant, and can be 5 V tolerant with an external 100 Ω resistor. PCI 5 V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT} . With Virtex-E devices, the LVTTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO} .

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 μ m CMOS process. These advances make Virtex-E FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The Virtex-E family includes the nine members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing

For in-circuit debugging, an optional download and read-back cable is available. This cable connects the FPGA in the target system to a PC or workstation. After downloading the design into the FPGA, the designer can single-step the

Configuration

Virtex-E devices are configured by loading configuration data into the internal configuration memory. Note that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Some of the pins used for configuration are dedicated pins, while others can be re-used as general purpose inputs and outputs once configuration is complete.

The following are dedicated pins:

- Mode pins (M2, M1, M0)
- Configuration clock pin (CCLK)
- PROGRAM pin
- DONE pin
- Boundary Scan pins (TDI, TDO, TMS, TCK)

Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or can be generated externally and provided to the FPGA as an input. The PROGRAM pin must be pulled High prior to reconfiguration.

Note that some configuration pins can act as outputs. For correct operation, these pins require a V_{CCO} of 3.3 V or 2.5 V. At 3.3 V the pins operate as LVTTTL, and at 2.5 V they

logic, readback the contents of the flip-flops, and so observe the internal logic state. Simple modifications can be downloaded into the system in a matter of minutes.

operate as LVCMOS. All affected pins fall in banks 2 or 3. The configuration pins needed for SelectMap (CS, Write) are located in bank 1.

Configuration Modes

Virtex-E supports the following four configuration modes.

- Slave-serial mode
- Master-serial mode
- SelectMAP mode
- Boundary Scan mode (JTAG)

The Configuration mode pins (M2, M1, M0) select among these configuration modes with the option in each case of having the IOB pins either pulled up or left floating prior to configuration. The selection codes are listed in [Table 8](#).

Configuration through the Boundary Scan port is always available, independent of the mode selection. Selecting the Boundary Scan mode simply turns off the other modes. The three mode pins have internal pull-up resistors, and default to a logic High if left unconnected. However, it is recommended to drive the configuration mode pins externally.

Table 8: Configuration Codes

Configuration Mode	M2 ⁽¹⁾	M1	M0	CCLK Direction	Data Width	Serial D _{out}	Configuration Pull-ups ⁽¹⁾
Master-serial mode	0	0	0	Out	1	Yes	No
Boundary Scan mode	1	0	1	N/A	1	No	No
SelectMAP mode	1	1	0	In	8	No	No
Slave-serial mode	1	1	1	In	1	Yes	No
Master-serial mode	1	0	0	Out	1	Yes	Yes
Boundary Scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Notes:

1. M2 is sampled continuously from power up until the end of the configuration. Toggling M2 while INIT is being held externally Low can cause the configuration pull-up settings to change.

the internal storage elements to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed. In addition, the GTS, GSR, and GWE events can be made depen-

Readback

The configuration data stored in the Virtex-E configuration memory can be readback for verification. Along with the configuration data it is possible to readback the contents all flip-flops/latches, LUT RAMs, and block RAMs. This capa-

Design Considerations

This section contains more detailed design information on the following features.

- Delay-Locked Loop . . . see [page 19](#)
- BlockRAM . . . see [page 24](#)
- SelectI/O . . . see [page 31](#)

Using DLLs

The Virtex-E FPGA series provides up to eight fully digital dedicated on-chip Delay-Locked Loop (DLL) circuits which provide zero propagation delay, low clock skew between output clock signals distributed throughout the device, and advanced clock domain control. These dedicated DLLs can be used to implement several circuits which improve and simplify system level design.

Introduction

As FPGAs grow in size, quality on-chip clock distribution becomes increasingly important. Clock skew and clock delay impact device performance and the task of managing clock skew and clock delay with conventional clock trees becomes more difficult in large devices. The Virtex-E series of devices resolve this potential problem by providing up to eight fully digital dedicated on-chip DLL circuits, which provide zero propagation delay and low clock skew between output clock signals distributed throughout the device.

Each DLL can drive up to two global clock routing networks within the device. The global clock distribution network minimizes clock skews due to loading differences. By monitoring a sample of the DLL output clock, the DLL can compensate for the delay on the routing network, effectively eliminating the delay from the external input port to the individual clock loads within the device.

In addition to providing zero delay with respect to a user source clock, the DLL can provide multiple phases of the source clock. The DLL can also act as a clock doubler or it can divide the user source clock by up to 16.

Clock multiplication gives the designer a number of design alternatives. For instance, a 50 MHz source clock doubled by the DLL can drive an FPGA design operating at 100 MHz. This technique can simplify board design because the clock path on the board no longer distributes such a

dent on the DONE pins of multiple devices all going High, forcing the devices to start synchronously. The sequence can also be paused at any stage until lock has been achieved on any or all DLLs.

bility is used for real-time debugging. For more detailed information, see application note XAPP138 "Virtex FPGA Series Configuration and Readback".

high-speed signal. A multiplied clock also provides designers the option of time-domain-multiplexing, using one circuit twice per clock cycle, consuming less area than two copies of the same circuit. Two DLLs in can be connected in series to increase the effective clock multiplication factor to four.

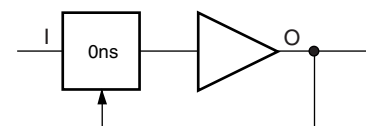
The DLL can also act as a clock mirror. By driving the DLL output off-chip and then back in again, the DLL can be used to deskew a board level clock between multiple devices.

In order to guarantee the system clock establishes prior to the device "waking up," the DLL can delay the completion of the device configuration process until after the DLL achieves lock.

By taking advantage of the DLL to remove on-chip clock delay, the designer can greatly simplify and improve system level design involving high-fanout, high-performance clocks.

Library DLL Symbols

Figure 21 shows the simplified Xilinx library DLL macro symbol, BUFGDLL. This macro delivers a quick and efficient way to provide a system clock with zero propagation delay throughout the device. **Figure 22** and **Figure 23** show the two library DLL primitives. These symbols provide access to the complete set of DLL features when implementing more complex applications.



ds022_25_121099

Figure 21: Simplified DLL Macro Symbol BUFGDLL

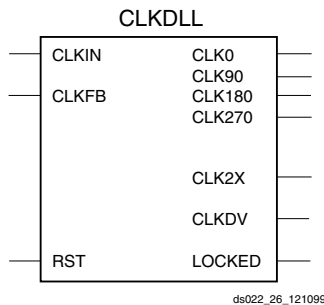


Figure 22: Standard DLL Symbol CLKDLL

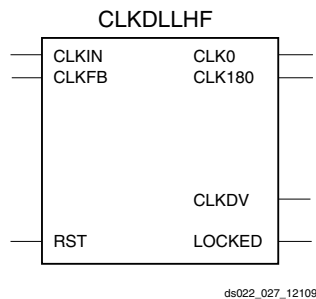


Figure 23: High Frequency DLL Symbol CLKDLLHF

BUFGDLL Pin Descriptions

Use the BUFGDLL macro as the simplest way to provide zero propagation delay for a high-fanout on-chip clock from an external input. This macro uses the IBUFG, CLKDLL and BUFG primitives to implement the most basic DLL application as shown in Figure 24.

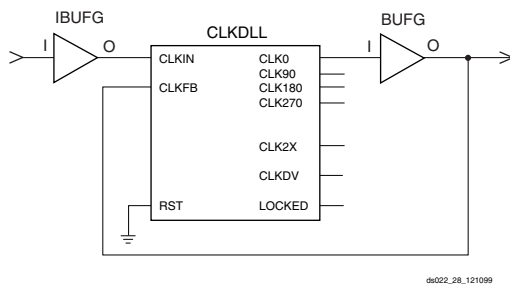


Figure 24: BUFGDLL Schematic

This symbol does not provide access to the advanced clock domain controls or to the clock multiplication or clock division features of the DLL. This symbol also does not provide access to the RST, or LOCKED pins of the DLL. For access to these features, a designer must use the library DLL primitives described in the following sections.

Source Clock Input — I

The I pin provides the user source clock, the clock signal on which the DLL operates, to the BUFGDLL. For the BUFGDLL macro the source clock frequency must fall in the low frequency range as specified in the data sheet. The BUF-

GDLL requires an external signal source clock. Therefore, only an external input port can source the signal that drives the BUFGDLL I pin.

Clock Output — O

The clock output pin O represents a delay-compensated version of the source clock (I) signal. This signal, sourced by a global clock buffer BUFG symbol, takes advantage of the dedicated global clock routing resources of the device.

The output clock has a 50-50 duty cycle unless you deactivate the duty cycle correction property.

CLKDLL Primitive Pin Descriptions

The library CLKDLL primitives provide access to the complete set of DLL features needed when implementing more complex applications with the DLL.

Source Clock Input — CLKIN

The CLKIN pin provides the user source clock (the clock signal on which the DLL operates) to the DLL. The CLKIN frequency must fall in the ranges specified in the data sheet. A global clock buffer (BUFG) driven from another CLKDLL, one of the global clock input buffers (IBUFG), or an IO_LVDS_DLL pin on the same edge of the device (top or bottom) must source this clock signal. There are four IO_LVDS_DLL input pins that can be used as inputs to the DLLs. This makes a total of eight usable input pins for DLLs in the Virtex-E family.

Feedback Clock Input — CLKFB

The DLL requires a reference or feedback signal to provide the delay-compensated output. Connect only the CLK0 or CLK2X DLL outputs to the feedback clock input (CLKFB) pin to provide the necessary feedback to the DLL. The feedback clock input can also be provided through one of the following pins.

IBUFG - Global Clock Input Pad

IO_LVDS_DLL - the pin adjacent to IBUFG

If an IBUFG sources the CLKFB pin, the following special rules apply.

1. An external input port must source the signal that drives the IBUFG I pin.
2. The CLK2X output must feedback to the device if both the CLK0 and CLK2X outputs are driving off chip devices.
3. That signal must directly drive only OBUFs and nothing else.

These rules enable the software determine which DLL clock output sources the CLKFB pin.

Reset Input — RST

When the reset pin RST activates the LOCKED signal deactivates within four source clock cycles. The RST pin, active High, must either connect to a dynamic signal or tied to

Initialization in Verilog and Synopsys

The block SelectRAM+ structures can be initialized in Verilog for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the Verilog code uses a defparam to pass the initialization. The Synopsys FPGA compiler does not presently support defparam. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the defparam statements. The following code illustrates a module that employs these techniques.

Design Examples

Creating a 32-bit Single-Port RAM

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single port, 128 deep by 32-bit wide RAM to be created using a single block SelectRAM+ cell as shown in **Figure 35**.

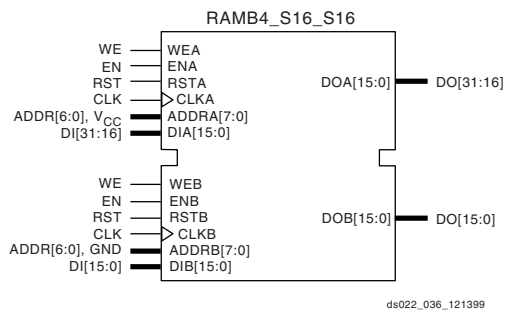


Figure 35: Single Port 128 x 32 RAM

Interleaving the memory space, setting the LSB of the address bus of Port A to 1 (V_{CC}), and the LSB of the

address bus of Port B to 0 (GND), allows a 32-bit wide single port RAM to be created.

Creating Two Single-Port RAMs

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single RAM to be split into two single port memories of 2K bits each as shown in **Figure 36**.

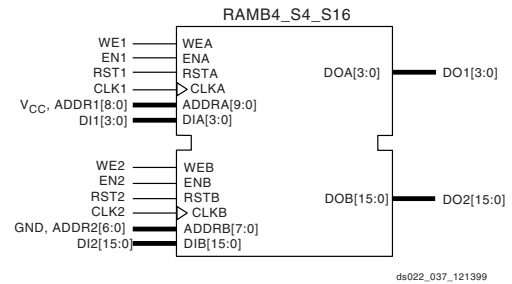


Figure 36: 512 x 4 RAM and 128 x 16 RAM

In this example, a 512K x 4 RAM (Port A) and a 128 x 16 RAM (Port B) are created out of a single block SelectRAM+. The address space for the RAM is split by fixing the MSB of Port A to 1 (V_{CC}) for the upper 2K bits and the MSB of Port B to 0 (GND) for the lower 2K bits.

Block Memory Generation

The CoreGen program generates memory structures using the block SelectRAM+ features. This program outputs VHDL or Verilog simulation code templates and an EDIF file for inclusion in a design.

VHDL Initialization Example

```

library IEEE;
use IEEE.std_logic_1164.all;

entity MYMEM is
port (CLK, WE:in std_logic;
ADDR: in std_logic_vector(8 downto 0);
DIN: in std_logic_vector(7 downto 0);
DOUT: out std_logic_vector(7 downto 0));
end MYMEM;

architecture BEHAVE of MYMEM is
signal logic0, logic1: std_logic;

component RAMB4_S8
--synopsys translate_off
generic( INIT_00,INIT_01, INIT_02, INIT_03, INIT_04, INIT_05, INIT_06, INIT_07,
INIT_08, INIT_09, INIT_0a, INIT_0b, INIT_0c, INIT_0d, INIT_0e, INIT_0f : BIT_VECTOR(255
downto 0)
:= X"0000000000000000000000000000000000000000000000000000000000000000");
--synopsys translate_on
port (WE, EN, RST, CLK: in STD_LOGIC;
ADDR: in STD_LOGIC_VECTOR(8 downto 0);
DI: in STD_LOGIC_VECTOR(7 downto 0);
DO: out STD_LOGIC_VECTOR(7 downto 0));
end component;

--synopsys dc_script_begin
--set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
--set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
--synopsys dc_script_end

begin
logic0 <='0';
logic1 <='1';

ram0: RAMB4_S8
--synopsys translate_off
generic map (
INIT_00 => X"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF",
INIT_01 => X"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210")
--synopsys translate_on
port map (WE=>WE, EN=>logic1, RST=>logic0, CLK=>CLK,ADDR=>ADDR, DI=>DIN, DO=>DOUT);
end BEHAVE;

```

Fundamentals

Modern bus applications, pioneered by the largest and most influential companies in the digital electronics industry, are commonly introduced with a new I/O standard tailored specifically to the needs of that application. The bus I/O standards provide specifications to other vendors who create products designed to interface with these applications. Each standard often has its own specifications for current, voltage, I/O buffering, and termination techniques.

The ability to provide the flexibility and time-to-market advantages of programmable logic is increasingly dependent on the capability of the programmable logic device to support an ever increasing variety of I/O standards

The SelectI/O resources feature highly configurable input and output buffers which provide support for a wide variety of I/O standards. As shown in [Table 18](#), each buffer type can support a variety of voltage requirements.

Table 18: Virtex-E Supported I/O Standards

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVC MOS2	2.5	2.5	N/A	N/A
LVC MOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

Overview of Supported I/O Standards

This section provides a brief overview of the I/O standards supported by all Virtex-E devices.

While most I/O standards specify a range of allowed voltages, this document records typical voltage values only. Detailed information on each specification can be found on the Electronic Industry Alliance Jedec website at:

<http://www.jedec.org>

LVTTL — Low-Voltage TTL

The Low-Voltage TTL, or LVTTL standard is a general purpose EIA/JESDSA standard for 3.3V applications that uses an LVTTL input buffer and a Push-Pull output buffer. This standard requires a 3.3V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a termination voltage (V_{TT}).

LVC MOS2 — Low-Voltage CMOS for 2.5 Volts

The Low-Voltage CMOS for 2.5 Volts or lower, or LVC MOS2 standard is an extension of the LVC MOS standard (JESD 8-5) used for general purpose 2.5V applications. This standard requires a 2.5V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}).

LVC MOS18 — 1.8 V Low Voltage CMOS

This standard is an extension of the LVC MOS standard. It is used in general purpose 1.8 V applications. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required.

PCI — Peripheral Component Interface

The Peripheral Component Interface, or PCI standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses a LVTTL input buffer and a Push-Pull output buffer. This standard does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}), however, it does require a 3.3V output source voltage (V_{CCO}).

GTL — Gunning Transceiver Logic Terminated

The Gunning Transceiver Logic, or GTL standard is a high-speed bus standard (JESD8.3) invented by Xerox. Xilinx has implemented the terminated variation for this standard. This standard requires a differential amplifier input buffer and an Open Drain output buffer.

GTL+ — Gunning Transceiver Logic Plus

The Gunning Transceiver Logic Plus, or GTL+ standard is a high-speed bus standard (JESD8.3) first used by the Pentium Pro processor.

HSTL — High-Speed Transceiver Logic

The High-Speed Transceiver Logic, or HSTL standard is a general purpose high-speed, 1.5V bus standard sponsored by IBM (EIA/JESD 8-6). This standard has four variations or classes. SelectI/O devices support Class I, III, and IV. This

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

```
map -pr b <filename>
```

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectI/O symbol with the location constraint LOC attached to the SelectI/O symbol. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

```
LOC=A42
```

```
LOC=P37
```

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programmed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

```
SLEW=SLOW
```

```
SLEW=FAST
```

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTTL output buffers (OBUF, OBUFT, and IOBUF), the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

```
DRIVE=2
```

```
DRIVE=4
```

```
DRIVE=6
```

```
DRIVE=8
```

```
DRIVE=12 (Default)
```

```
DRIVE=16
```

```
DRIVE=24
```

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is “banked” within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See [Figure 38](#) for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectI/O devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

IOB Input Switching Characteristics Standard Adjustments

			Speed Grade ⁽¹⁾				Units
Description	Symbol	Standard	Min	-8	-7	-6	
Data Input Delay Adjustments							
Standard-specific data input delay adjustments	T _{ILVTTL}	LVTTTL	0.0	0.0	0.0	0.0	ns
	T _{ILVCMOS2}	LVC MOS2	−0.02	0.0	0.0	0.0	ns
	T _{ILVCMOS18}	LVC MOS18	0.12	+0.20	+0.20	+0.20	ns
	T _{ILVDS}	LVDS	0.00	+0.15	+0.15	+0.15	ns
	T _{ILVPECL}	LVPECL	0.00	+0.15	+0.15	+0.15	ns
	T _{IPCI33_3}	PCI, 33 MHz, 3.3 V	−0.05	+0.08	+0.08	+0.08	ns
	T _{IPCI66_3}	PCI, 66 MHz, 3.3 V	−0.05	−0.11	−0.11	−0.11	ns
	T _{IGTL}	GTL	+0.10	+0.14	+0.14	+0.14	ns
	T _{IGTLPLUS}	GTL+	+0.06	+0.14	+0.14	+0.14	ns
	T _{IHSTL}	HSTL	+0.02	+0.04	+0.04	+0.04	ns
	T _{ISSTL2}	SSTL2	−0.04	+0.04	+0.04	+0.04	ns
	T _{ISSTL3}	SSTL3	−0.02	+0.04	+0.04	+0.04	ns
	T _{ICTT}	CTT	+0.01	+0.10	+0.10	+0.10	ns
	T _{IAGP}	AGP	−0.03	+0.04	+0.04	+0.04	ns

Notes:

- Input timing t_i for LVTTTL is measured at 1.4 V. For other I/O standards, see [Table 4](#).

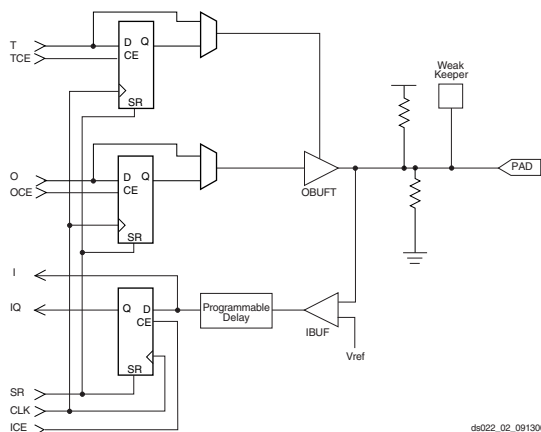


Figure 1: Virtex-E Input/Output Block (IOB)

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P74	IO_L43P_YY	5
P73 ¹	IO_VREF_L43N_YY	5
P72	IO	5
P71	IO_L44P_YY	5
P70	IO_VREF_L44N_YY	5
P68	IO_L45P_YY	5
P67	IO_L45N_YY	5
P66 ²	IO_VREF_L46P_Y	5
P65	IO_L46N_Y	5
P64	IO_L47P_YY	5
P63	IO_L47N_YY	5
P57	IO_L48N_YY	6
P56	IO_L48P_YY	6
P54 ²	IO_VREF	6
P53	IO_L49N_Y	6
P52	IO_L49P_Y	6
P50	IO_VREF_L50N_Y	6
P49	IO_L50P_Y	6
P48	IO	6
P47 ¹	IO_VREF_L51N_Y	6
P46	IO_L51P_Y	6
P42	IO_L52N_YY	6
P41	IO_L52P_YY	6
P40	IO	6
P39	IO_L53N_Y	6
P38	IO_L53P_Y	6
P36	IO_VREF_L54N_Y	6
P35	IO_L54P_Y	6
P34	IO_L55N_Y	6
P33 ³	IO_VREF_L55P_Y	6
P31	IO	6
P28	IO_L56N_YY	7
P27	IO_L56P_YY	7

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P26 ³	IO_VREF	7
P24	IO_L57N_Y	7
P23	IO_VREF_L57P_Y	7
P21	IO_L58N_Y	7
P20	IO_L58P_Y	7
P19	IO	7
P18	IO_L59N_YY	7
P17	IO_L59P_YY	7
P13	IO_L60N_Y	7
P12 ¹	IO_VREF_L60P_Y	7
P11	IO	7
P10	IO_L61N_Y	7
P9	IO_VREF_L61P_Y	7
P7	IO_L62N_Y	7
P6	IO_L62P_Y	7
P5 ²	IO_VREF_L63N_Y	7
P4	IO_L63P_Y	7
P3	IO	7
P179	CCLK	2
P120	DONE	3
P60	M0	NA
P58	M1	NA
P62	M2	NA
P122	PROGRAM	NA
P183	TDI	NA
P239	TCK	NA
P181	TDO	2
P2	TMS	NA
P225	VCCINT	NA
P214	VCCINT	NA
P198	VCCINT	NA
P164	VCCINT	NA
P148	VCCINT	NA

BG432 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 13: BG432 Differential Pin Pair Summary
XCV300E, XCV400E, XC600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	AL16	AH15	NA	IO_DLL_L86P
1	5	AK16	AL17	NA	IO_DLL_L86N
2	1	A16	B16	NA	IO_DLL_L16P
3	0	D17	C17	NA	IO_DLL_L16N
IO LVDS					
Total Outputs: 137, Asynchronous Output Pairs: 63					
0	0	D27	B29	1	-
1	0	C27	B28	✓	-
2	0	A28	D26	✓	VREF
3	0	C26	B27	2	-
4	0	A27	D25	✓	-
5	0	C25	D24	✓	VREF
6	0	D23	B25	1	-
7	0	B24	C24	1	VREF
8	0	A24	D22	✓	VREF
9	0	B22	C22	✓	-
10	0	D20	C21	✓	-
11	0	C20	B21	✓	-
12	0	D19	A20	✓	-
13	0	A19	B19	✓	VREF
14	0	D18	B18	1	-
15	0	B17	C18	1	VREF

Table 13: BG432 Differential Pin Pair Summary
XCV300E, XCV400E, XC600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	1	B16	C17	NA	IO_LVDS_DLL
17	1	B15	A15	1	VREF
18	1	D15	C15	1	-
19	1	A13	B14	✓	VREF
20	1	D14	B13	✓	-
21	1	B12	C13	✓	-
22	1	C12	D13	✓	-
23	1	C11	D12	✓	-
24	1	C10	B10	✓	VREF
25	1	D10	C9	1	VREF
26	1	B8	A8	1	-
27	1	B7	C8	✓	VREF
28	1	A6	D8	✓	-
29	1	D7	B6	2	-
30	1	C6	A5	✓	VREF
31	1	D6	B5	✓	-
32	1	C5	A4	1	-
33	1	D5	B4	✓	CS, WRITE
34	2	D3	C2	✓	DIN, D0, BUSY
35	2	D2	E4	3	-
36	2	D1	E3	4	-
37	2	E2	F4	1	VREF
38	2	E1	F3	5	-
39	2	F2	G4	1	-
40	2	G3	G2	✓	VREF
41	2	H3	H2	4	-
42	2	H1	J4	1	VREF
43	2	J2	K4	✓	D1
44	2	K2	K1	✓	D2
45	2	L2	M4	4	-
46	2	M3	M2	1	-
47	2	N4	N3	1	-

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
4	IO_L104N_YY	AJ12	
4	IO_L105P_Y	AN11	
4	IO_L105N_Y	AK12	
4	IO_L106P_YY	AL12	
4	IO_L106N_YY	AM12	
4	IO_VREF_L107P_YY	AK13	3
4	IO_L107N_YY	AL13	
4	IO_L108P_Y	AM13	
4	IO_L108N_Y	AN13	
4	IO_L109P_YY	AJ14	
4	IO_L109N_YY	AK14	
4	IO_VREF_L110P_YY	AM14	
4	IO_L110N_YY	AN15	
4	IO_L111P_Y	AJ15	
4	IO_L111N_Y	AK15	
4	IO_L112P_Y	AL15	
4	IO_L112N_Y	AM16	
4	IO_VREF_L113P_Y	AL16	
4	IO_L113N_Y	AJ16	
4	IO_L114P_Y	AK16	
4	IO_VREF_L114N_Y	AN17	2
4	IO_LVDS_DLL_L115P	AM17	
5	GCK1	AJ17	
5	IO	AL25	
5	IO	AL28	
5	IO	AL30	
5	IO	AN28	
5	IO_LVDS_DLL_L115N	AM18	
5	IO_VREF	AL18	2
5	IO_L116P_Y	AK18	
5	IO_VREF_L116N_Y	AJ18	
5	IO_L117P_Y	AN19	
5	IO_L117N_Y	AL19	
5	IO_L118P_Y	AK19	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
5	IO_L118N_Y	AM20	
5	IO_L119P_YY	AJ19	
5	IO_VREF_L119N_YY	AL20	
5	IO_L120P_YY	AN21	
5	IO_L120N_YY	AL21	
5	IO_L121P_Y	AJ20	
5	IO_L121N_Y	AM22	
5	IO_L122P_YY	AK21	
5	IO_VREF_L122N_YY	AN23	3
5	IO_L123P_YY	AJ21	
5	IO_L123N_YY	AM23	
5	IO_L124P_Y	AK22	
5	IO_L124N_Y	AM24	
5	IO_L125P_YY	AL23	
5	IO_L125N_YY	AJ22	
5	IO_L126P_YY	AK23	
5	IO_VREF_L126N_YY	AL24	
5	IO_L127P_Y	AN26	
5	IO_L127N_Y	AJ23	
5	IO_L128P_Y	AK24	
5	IO_VREF_L128N_Y	AM26	4
5	IO_L129P_Y	AM27	
5	IO_L129N_Y	AJ24	
5	IO_L130P_Y	AL26	
5	IO_VREF_L130N_Y	AK25	1
5	IO_L131P_YY	AN29	
5	IO_VREF_L131N_YY	AJ25	
5	IO_L132P_YY	AK26	
5	IO_L132N_YY	AM29	
5	IO_L133P_Y	AM30	
5	IO_L133N_Y	AJ26	
5	IO_L134P_YY	AK27	
5	IO_VREF_L134N_YY	AL29	
5	IO_L135P_YY	AN31	
5	IO_L135N_YY	AJ27	

Table 15: BG560 Differential Pin Pair Summary
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
109	4	AJ14	AK14	√	-
110	4	AM14	AN15	√	VREF
111	4	AJ15	AK15	1	-
112	4	AL15	AM16	7	-
113	4	AL16	AJ16	7	VREF
114	4	AK16	AN17	2	VREF
115	5	AM17	AM18	NA	IO_LVDS_DLL
116	5	AK18	AJ18	7	VREF
117	5	AN19	AL19	7	-
118	5	AK19	AM20	9	-
119	5	AJ19	AL20	√	VREF
120	5	AN21	AL21	√	-
121	5	AJ20	AM22	3	-
122	5	AK21	AN23	√	VREF
123	5	AJ21	AM23	√	-
124	5	AK22	AM24	8	-
125	5	AL23	AJ22	√	-
126	5	AK23	AL24	√	VREF
127	5	AN26	AJ23	13	-
128	5	AK24	AM26	7	VREF
129	5	AM27	AJ24	7	-
130	5	AL26	AK25	5	VREF
131	5	AN29	AJ25	√	VREF
132	5	AK26	AM29	√	-
133	5	AM30	AJ26	11	-
134	5	AK27	AL29	√	VREF
135	5	AN31	AJ27	√	-
136	5	AM31	AK28	12	VREF
137	6	AJ30	AH29	√	-
138	6	AH30	AK31	17	VREF
139	6	AJ31	AG29	14	-

Table 15: BG560 Differential Pin Pair Summary
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
140	6	AG30	AK32	15	VREF
141	6	AF29	AH31	16	-
142	6	AF30	AH32	15	-
143	6	AH33	AE29	√	VREF
144	6	AE30	AG33	17	VREF
145	6	AF32	AD29	14	-
146	6	AD30	AE31	18	VREF
147	6	AC29	AE32	19	-
148	6	AC30	AD31	√	VREF
149	6	AC31	AB29	√	-
150	6	AB30	AC33	17	-
151	6	AA29	AB31	14	-
152	6	AA31	AA30	15	VREF
153	6	Y29	AA32	16	-
154	6	Y30	AA33	15	-
155	6	W29	Y32	√	VREF
156	6	W31	W30	17	-
157	6	V30	W33	14	-
158	6	V31	V29	18	VREF
159	6	U33	V32	19	VREF
160	7	U32	U31	√	-
161	7	T30	T32	19	VREF
162	7	T31	T29	18	VREF
163	7	R31	R33	14	-
164	7	R29	R30	17	-
165	7	P31	P32	√	VREF
166	7	P29	P30	15	-
167	7	N31	M32	16	-
168	7	L33	N30	15	VREF
169	7	L32	M31	14	-
170	7	L31	M30	17	-

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
7	IO_L74N_Y	G4
7	IO_VREF_L74P_Y	H3
7	IO_L75N_YY	G2
7	IO_L75P_YY	F5
7	IO_L76N	F4
7	IO_L76P	F1
7	IO_L77N_YY	G3
7	IO_L77P_YY	F2
7	IO_L78N_Y	E1
7	IO_VREF_L78P_Y	D1 ¹
7	IO_L79N	E4
7	IO_L79P	E2
7	IO_L80N_Y	F3
7	IO_VREF_L80P_Y	C1
7	IO_L81N_YY	D2
7	IO_L81P_YY	E3
7	IO_VREF_L82N	B1 ²
7	IO_L82P	A2
2	CCLK	D15
3	DONE	R14
NA	DXN	R4
NA	DXP	P4
NA	M0	N3
NA	M1	P2
NA	M2	R3
NA	PROGRAM	P15
NA	TCK	C4
NA	TDI	A15
2	TDO	B14
NA	TMS	D3
NA	VCCINT	C3
NA	VCCINT	C14
NA	VCCINT	D4

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
NA	VCCINT	D13
NA	VCCINT	E5
NA	VCCINT	E12
NA	VCCINT	M5
NA	VCCINT	M12
NA	VCCINT	N4
NA	VCCINT	N13
NA	VCCINT	P3
NA	VCCINT	P14
0	VCCO	F8
0	VCCO	E8
1	VCCO	F9
1	VCCO	E9
2	VCCO	H12
2	VCCO	H11
3	VCCO	J12
3	VCCO	J11
4	VCCO	M9
4	VCCO	L9
5	VCCO	M8
5	VCCO	L8
6	VCCO	J6
6	VCCO	J5
7	VCCO	H6
7	VCCO	H5
NA	GND	T16
NA	GND	T1
NA	GND	R15
NA	GND	R2
NA	GND	L11
NA	GND	L10
NA	GND	L7
NA	GND	L6

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
0	VCCO	E34
0	VCCO	E33
0	VCCO	E30
0	VCCO	E29
0	VCCO	E27
0	VCCO	E26
1	VCCO	E10
1	VCCO	E11
1	VCCO	E13
1	VCCO	E14
1	VCCO	E6
1	VCCO	E7
2	VCCO	P5
2	VCCO	N5
2	VCCO	L5
2	VCCO	K5
2	VCCO	G5
2	VCCO	F5
3	VCCO	AP5
3	VCCO	AN5
3	VCCO	AK5
3	VCCO	AJ5
3	VCCO	AG5
3	VCCO	AF5
4	VCCO	AR10
4	VCCO	AR11
4	VCCO	AR13
4	VCCO	AR14
4	VCCO	AR6
4	VCCO	AR7
5	VCCO	AR34
5	VCCO	AR33
5	VCCO	AR30
5	VCCO	AR29
5	VCCO	AR27

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
5	VCCO	AR26
6	VCCO	AP35
6	VCCO	AN35
6	VCCO	AK35
6	VCCO	AJ35
6	VCCO	AG35
6	VCCO	AF35
7	VCCO	P35
7	VCCO	N35
7	VCCO	L35
7	VCCO	K35
7	VCCO	G35
7	VCCO	F35
NA	GND	Y5
NA	GND	Y4
NA	GND	Y37
NA	GND	Y36
NA	GND	Y35
NA	GND	Y3
NA	GND	W5
NA	GND	W35
NA	GND	M5
NA	GND	M4
NA	GND	M36
NA	GND	M35
NA	GND	E5
NA	GND	E35
NA	GND	E28
NA	GND	E21
NA	GND	E20
NA	GND	E19
NA	GND	E12
NA	GND	D4
NA	GND	D36
NA	GND	D28

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	3	AN4	AT1	4	-
121	3	AR2	AP4	4	VREF
122	3	AT2	AR3	6	-
123	3	AR4	AU2	√	INIT
124	4	AU4	AV5	√	-
125	4	AT6	AV4	5	-
126	4	AU6	AW4	5	VREF
127	4	AT7	AW5	√	-
128	4	AU7	AV6	√	VREF
129	4	AT8	AW6	3	-
130	4	AU8	AV7	3	-
131	4	AT9	AW7	√	-
132	4	AV8	AU9	√	VREF
133	4	AW8	AT10	5	-
134	4	AV9	AU10	5	VREF
135	4	AW9	AT11	√	-
136	4	AV10	AU11	√	VREF
137	4	AW10	AU12	2	-
138	4	AV11	AT13	2	-
139	4	AW11	AU13	√	VREF
140	4	AT14	AV12	√	-
141	4	AU14	AW12	5	-
142	4	AT15	AV13	5	-
143	4	AU15	AW13	√	-
144	4	AV14	AT16	√	VREF
145	4	AW14	AU16	3	-
146	4	AV15	AR17	3	-
147	4	AW15	AT17	√	-
148	4	AU17	AV16	√	VREF
149	4	AR18	AW16	5	-
150	4	AT18	AV17	5	-
151	4	AU18	AW17	√	-
152	4	AT19	AV18	√	VREF
153	4	AU19	AW18	2	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	4	AU21	AV19	2	VREF
155	5	AT21	AT22	NA	IO_LVDS_DLL
156	5	AV20	AR22	8	VREF
157	5	AV23	AW21	√	VREF
158	5	AU23	AV21	√	-
159	5	AT23	AW22	5	-
160	5	AR23	AV22	5	-
161	5	AV24	AW23	√	VREF
162	5	AW24	AU24	√	-
163	5	AW25	AT24	3	-
164	5	AV25	AU25	3	-
165	5	AW26	AT25	√	VREF
166	5	AV26	AW27	√	-
167	5	AU26	AV27	5	-
168	5	AT26	AW28	5	-
169	5	AU27	AV28	√	-
170	5	AW29	AT27	√	VREF
171	5	AW30	AU28	2	-
172	5	AV30	AV29	2	-
173	5	AW31	AU29	√	VREF
174	5	AV31	AT29	√	-
175	5	AW32	AU30	5	VREF
176	5	AW33	AT30	5	-
177	5	AV33	AU31	√	VREF
178	5	AT31	AW34	√	-
179	5	AV32	AV34	3	-
180	5	AU32	AW35	3	-
181	5	AT32	AV35	√	VREF
182	5	AU33	AW36	√	-
183	5	AT33	AV36	5	VREF
184	5	AU34	AU36	5	-
185	6	AT38	AR36	√	-
186	6	AP36	AR38	6	-
187	6	AP37	AT39	4	VREF

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
256	7	T38	T41	√	-
257	7	T42	R39	1	VREF
258	7	R38	R42	2	-
259	7	P39	R40	4	-
260	7	P38	R41	2	-
261	7	N39	P42	1	-
262	7	M39	P40	3	-
263	7	M38	P41	√	-
264	7	L39	N42	√	VREF
265	7	N41	L38	2	-
266	7	M42	K40	√	-
267	7	K38	M40	√	VREF
268	7	J40	M41	2	-
269	7	L40	J39	5	VREF
270	7	L41	J38	√	-
271	7	H39	K42	√	VREF
272	7	H38	K41	1	-
273	7	G40	J41	2	-
274	7	G39	H42	√	-
275	7	G42	G38	1	VREF
276	7	F40	G41	2	-
277	7	F41	F42	4	-
278	7	E42	F39	2	VREF
279	7	E41	E40	1	-
280	7	D41	E39	3	-

Notes:

1. AO in the XCV1000E, 2000E.
2. AO in the XCV1000E, 1600E.
3. AO in the XCV2000E.
4. AO in the XCV1600E.
5. AO in the XCV1000E.

FG900 Fine-Pitch Ball Grid Array Package

XCV600E, XCV1000E, and XCV1600E devices in the FG900 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF} , it can be used as general I/O. Immediately following [Table 26](#), see [Table 27](#) for Differential Pair information.

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	GCK3	C15
0	IO	A7 ⁴
0	IO	A13 ⁴
0	IO	C5 ⁴
0	IO	C6 ⁴
0	IO	C14 ⁴
0	IO	D8 ⁵
0	IO	D10
0	IO	D13 ⁴
0	IO	E6
0	IO	E9 ⁵
0	IO	E14 ⁵
0	IO	F9 ⁴
0	IO	F14 ⁵
0	IO	G15
0	IO	K11 ⁵
0	IO	K12
0	IO	L13 ⁴
0	IO_L0N_YY	C4 ⁴
0	IO_L0P_YY	F7 ³
0	IO_L1N_Y	D5
0	IO_L1P_Y	G8
0	IO_VREF_L2N_Y	A3 ¹
0	IO_L2P_Y	H9
0	IO_L3N_Y	B4 ⁴
0	IO_L3P_Y	J10 ⁴
0	IO_L4N_YY	A4
0	IO_L4P_YY	D6
0	IO_VREF_L5N_YY	E7
0	IO_L5P_YY	B5

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
2	IO_L99P_YY	N26
2	IO_L99N_YY	P28
2	IO_L100P	P29
2	IO_L100N	N24
2	IO_L101P_YY	P22
2	IO_L101N_YY	R26
2	IO_VREF_L102P_YY	P25
2	IO_L102N_YY	R29
2	IO_L103P_YY	R21 ⁴
2	IO_L103N_YY	R28 ³
2	IO_VREF_L104P_YY	R25 ²
2	IO_L104N_YY	T30
2	IO_L105P_YY	P24 ⁴
2	IO_L105N_YY	R27 ³
2	IO_L106P	R24
3	IO	T22 ⁴
3	IO	T24 ⁴
3	IO	T26 ⁴
3	IO	T29 ⁴
3	IO	U26 ⁵
3	IO	V23 ⁴
3	IO	V25 ⁴
3	IO	V30 ⁵
3	IO	Y21 ⁴
3	IO	AA26 ⁴
3	IO	AA23 ⁴
3	IO	AB27 ⁴
3	IO	AB29 ⁴
3	IO	AC28 ⁵
3	IO	AD26 ⁴
3	IO	AD29 ⁵
3	IO	AE27 ⁵
3	IO_L106N	U29
3	IO_L107P_YY	R22
3	IO_VREF_L107N_YY	T27 ²
3	IO_L108P_YY	R23

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
3	IO_L108N_YY	T28
3	IO_L109P_YY	T21
3	IO_VREF_L109N_YY	T25
3	IO_L110P_YY	U28
3	IO_L110N_YY	U30
3	IO_L111P	T23
3	IO_L111N	U27
3	IO_L112P_YY	U25
3	IO_L112N_YY	V27
3	IO_D4_L113P_YY	U24
3	IO_VREF_L113N_YY	V29
3	IO_L114P	W30
3	IO_L114N	U22
3	IO_L115P_YY	U21
3	IO_L115N_YY	W29
3	IO_L116P_YY	V26
3	IO_L116N_YY	W27
3	IO_L117P	W26
3	IO_VREF_L117N	Y29 ¹
3	IO_L118P_YY	W25
3	IO_L118N_YY	Y30
3	IO_L119P_Y	V24 ⁴
3	IO_L119N_Y	Y28 ⁴
3	IO_L120P_YY	AA30
3	IO_L120N_YY	W24
3	IO_L121P	AA29
3	IO_L121N	V20
3	IO_L122P	Y27 ⁴
3	IO_L122N	W23 ⁴
3	IO_L123P_YY	Y26
3	IO_D5_L123N_YY	AB30
3	IO_D6_L124P_YY	V21
3	IO_VREF_L124N_YY	AA28
3	IO_L125P_YY	Y25
3	IO_L125N_YY	AA27
3	IO_L126P_YY	W22
3	IO_L126N_YY	Y23

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO_L154N	AG23
4	IO_L155P_YY	AF22
4	IO_L155N_YY	AE22
4	IO_VREF_L156P_YY	AJ22
4	IO_L156N_YY	AG22
4	IO_L157P	AK24 ⁴
4	IO_L157N	AD20 ³
4	IO_L158P_YY	AA19
4	IO_L158N_YY	AF21
4	IO_L159P	AH22 ⁴
4	IO_VREF_L159N	AA18
4	IO_L160P	AG21
4	IO_L160N	AK23
4	IO_L161P_YY	AH21 ⁴
4	IO_L161N_YY	AD19 ⁴
4	IO_L162P	AE20
4	IO_L162N	AJ21
4	IO_L163P	AG20
4	IO_L163N	AF20
4	IO_L164P	AC18 ⁴
4	IO_L164N	AF19 ⁴
4	IO_L165P_YY	AJ20
4	IO_L165N_YY	AE19
4	IO_VREF_L166P_YY	AK22 ¹
4	IO_L166N_YY	AH20
4	IO_L167P	AG19
4	IO_L167N	AB17
4	IO_L168P	AJ19
4	IO_L168N	AD17
4	IO_L169P_YY	AA16
4	IO_L169N_YY	AA17
4	IO_VREF_L170P_YY	AK21
4	IO_L170N_YY	AB16
4	IO_L171P	AG18
4	IO_L171N	AK20
4	IO_L172P	AK19
4	IO_L172N	AD16

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO_L173P_YY	AE16
4	IO_L173N_YY	AE17
4	IO_VREF_L174P_YY	AG17
4	IO_L174N_YY	AJ17
4	IO_L175P	AD15 ⁴
4	IO_L175N	AH17 ³
4	IO_VREF_L176P_YY	AG16 ²
4	IO_L176N_YY	AK17
4	IO_LVDS_DLL_L177P	AF16
5	GCK1	AK16
5	IO	AA11 ⁴
5	IO	AA14 ⁴
5	IO	AD14 ⁴
5	IO	AE7 ⁵
5	IO	AE8 ⁵
5	IO	AE10 ⁴
5	IO	AF6 ⁴
5	IO	AF10 ⁴
5	IO	AG9 ⁴
5	IO	AG12 ⁴
5	IO	AG14 ⁵
5	IO	AH8 ⁴
5	IO	AK6 ⁵
5	IO	AK14 ⁵
5	IO	AJ13 ⁴
5	IO	AJ15 ⁴
5	IO_LVDS_DLL_L177N	AH16
5	IO_L178P_YY	AC15 ⁴
5	IO_VREF_L178N_YY	AG15 ^{2,3}
5	IO_L179P_YY	AB15
5	IO_L179N_YY	AF15
5	IO_L180P_YY	AA15
5	IO_VREF_L180N_YY	AF14
5	IO_L181P_YY	AH15
5	IO_L181N_YY	AK15
5	IO_L182P	AB14

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCO_7	K5
NA	VCCO_7	F1
NA	VCCO_7	T11
NA	VCCO_7	T12
NA	VCCO_7	R11
NA	VCCO_7	R12
NA	VCCO_7	P3
NA	VCCO_7	P11
NA	VCCO_7	P12
NA	VCCO_7	N11
NA	GND	K32
NA	GND	R4
NA	GND	AN1
NA	GND	AM11
NA	GND	AK5
NA	GND	AH28
NA	GND	AD32
NA	GND	AA20
NA	GND	Y20
NA	GND	W19
NA	GND	V19
NA	GND	U20
NA	GND	T20
NA	GND	R19
NA	GND	P19
NA	GND	H8
NA	GND	F12
NA	GND	C2
NA	GND	B1
NA	GND	A7
NA	GND	AP1
NA	GND	AN2
NA	GND	AM15

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	GND	AK17
NA	GND	AH34
NA	GND	AC6
NA	GND	AA21
NA	GND	Y21
NA	GND	W20
NA	GND	V20
NA	GND	U21
NA	GND	T21
NA	GND	R20
NA	GND	P20
NA	GND	H16
NA	GND	F23
NA	GND	C3
NA	GND	B2
NA	GND	A28
NA	GND	AP34
NA	GND	AM3
NA	GND	AL31
NA	GND	AH7
NA	GND	AD3
NA	GND	AA19
NA	GND	Y19
NA	GND	W18
NA	GND	V18
NA	GND	U19
NA	GND	T19
NA	GND	R18
NA	GND	P18
NA	GND	J26
NA	GND	F6
NA	GND	C1
NA	GND	C34
NA	GND	A3